

Description

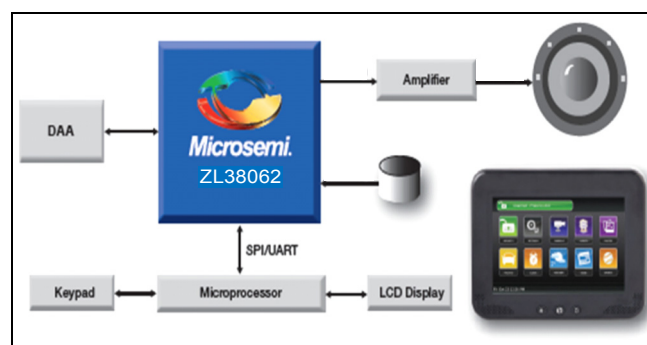
The ZL38062 is part of Microsemi's new Timberwolf audio processor family of products that feature the company's innovative *AcuEdge* acoustic technology, which is a set of highly-complex and integrated algorithms. These algorithms are incorporated into a powerful DSP platform that allow the user to extract intelligible information from the audio environment.

The Microsemi *AcuEdge* Technology ZL38062 device is ideal for Connected Home applications. Its license-free, royalty-free intelligent ZLS38062 audio Firmware provides Sound Classification capabilities, Acoustic Echo Cancellation (AEC), Noise Reduction (NR) and a variety of other voice enhancements to improve both the intelligibility and subjective quality of voice in harsh acoustic environments.

Microsemi offers additional tools to speed up the product development cycle. The *MiTuner*™ ZLS38508 or ZLS38508LITE GUI software packages allow a user to interactively configure the ZL38062 device. The optional *MiTuner* ZLE38470BADA Automatic Tuning Kit provides automatic tuning and easy control for manual fine tuning adjustments.

Applications

- Security cameras and monitoring systems
- Smoke/Fire and Carbon Monoxide alert reporting
- Integrated smart home gateways
- Intercoms



Connected Wallpad Block Diagram

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Version 7

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Ordering Information

Device OPN	Package	Packing
ZL38062LDF1	64-pin QFN (9x9)	Tape & Reel
ZL38062LDG1	64-pin QFN (9x9)	Tray
ZL38062UGB2	56-ball WLCSP (3.1x3.1)	Tape & Reel

These packages meet RoHS 2 Directive 2011/65/EU of the European Council to minimize the environmental impact of electrical equipment.

Microsemi *AcuEdge* Technology ZLS38062 Firmware

There are three Firmware images that may be selected to provide the desired operational mode. Firmware images can be swapped during normal operation to switch modes dynamically. Firmware image size varies with firmware load.

ZLS38062.1 (Alarm Detector)

- Detects T3 (Temporal smoke alarm) signals
- Detects T4 (Temporal carbon monoxide alarm) signals
- Low power listening mode

ZLS38062.2 (Glass Break and Energy Detectors)

- Detects the sound of breaking glass
- Programmable Energy Detector
- Detects T3 (Temporal smoke alarm) signals
- Detects T4 (Temporal carbon monoxide alarm) signals

ZLS38062.0 (Full Duplex Communication)

- Full Narrowband and Wideband Acoustic Echo cancellation operation
 - Supports long tail AEC (up to 256 ms)
 - Non-Linear AEC provides higher tolerance for speaker distortions
 - Non-Linear processor
- G.168 Line Echo Canceller
- Howling detection/cancellation
 - Prevents oscillation in AEC audio path
- Advanced noise reduction reduces background noise from the near-end speech signal using Psychoacoustic techniques

ZLS38062.0 (Full Duplex Communication) (cont.)

- Provisions for stereo audio mixing (sample rate of 44.1 or 48 kHz) and stereo music record and playback (sample rate of 48 kHz) with 8 kHz or 16 kHz voice processing
- Various encoding/decoding options:
 - 16-bit linear, G.722, G.711 A/μlaw
- Send and receive path equalizers
- Caller ID Type 1 & 2
- Programmable tone generation
- DTMF detection
- Dual $\Delta\Sigma$ 16-bit digital-to-analog converters (DAC)
 - Sampling up to 48 kHz and internal output drivers
 - Headphone amps capable of 4 single-ended or 2 differential outputs
 - 32 mW output drive power into 16 ohms
 - Impulse pop/click protection
- 1 Digital Microphone inputs supporting 1 or 2 Microphones
- 2 TDM ports shared between PCM and Inter-IC Sound (I²S)
 - Each port can be a clock master or a slave
 - Each port supports delayed and non-delayed (GCI) timing and I²S normal and left justified modes
 - Each port provides sample rate conversion and synchronous TDM bus operation

ZL38062 Hardware Features

- DSP with Voice Hardware Accelerators
- SPI or I²C Slave port for host processor interface
- General purpose UART port for debug
- Master SPI port for serial Flash interface
- Boots from SPI or Flash
 - Can run unattended (controllerless), self-booting into a configured operational state
 - Flash firmware can be updated from SPI Slave
- 14 General Purpose Input/Output (GPIO) pins (11 in WLCSP)
- 2 low power modes controlled by reset

The *MiTuner*™ Automatic Tuning Kit and ZLS38508 MiTuner GUI

Microsemi's Automatic Tuning Kit option includes:

- Audio Interface Box hardware
- Microphone and Speaker
- ZLS38508 *MiTuner* GUI software
 - Allows tuning of Microsemi's *AcuEdge* Technology Audio Processor

The ZLS38508 software features:

- Auto Tuning and Subjective Tuning support
- Allows tuning of key parameters of the system design
- Provides visual representations of the audio paths with drop-down menus to program parameters, allowing:
 - Control of the audio routing configuration
 - Programming of key building blocks in the transmit (Tx) and receive (Rx) audio paths
 - Setting analog and digital gains
- Configuration parameters allow users to “fine tune” the overall performance

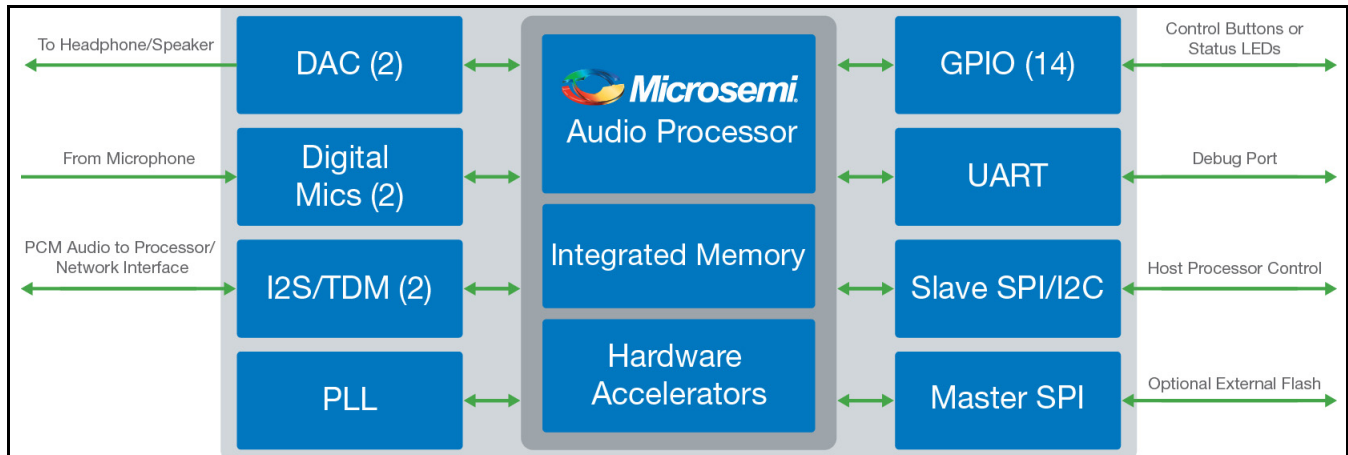


Tools

- ZLK38000 Evaluation Kit
- *MiTuner*™ ZLS38508 and ZLS38508LITE GUI
- *MiTuner*™ ZLE38470BADA Automatic Tuning Kit

Device Block Diagram

Figure 1 - ZL38062 Sound Classifier Audio Processor shown with Full Duplex Communication Firmware



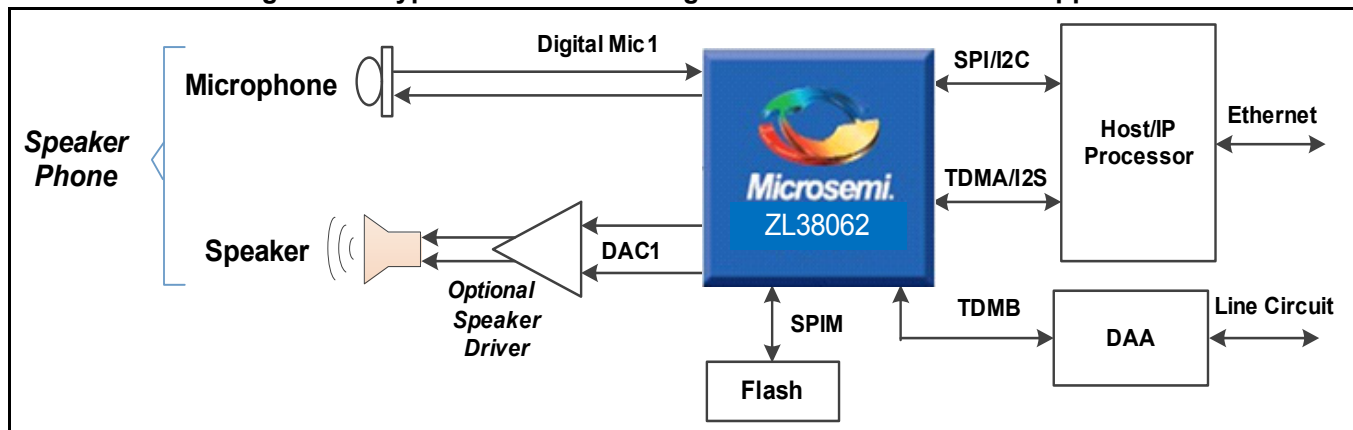
Applications

The Connected Home is about enabling users to talk to each other through connected devices. Connected devices could include integrated smart home gateways, intercoms, Media Centers, or IP Cameras. Microsemi *AcuEdge*™ Technology enables the full duplex operation between the connected devices to deliver on seamless high definition (HD) voice communication in complex noise environments such as gaming rooms and building lobbies.

The ZL38062 has two primary modes of operation: Alarm, Glass Break and Energy Detector mode (low power monitoring, sound detection, and reporting), and Full Duplex Communications mode. The ZLS38062.0 firmware provides the Full Duplex communications mode, while the other firmware variants (ZLS38062.1, ZLS38062.2) provide various Sound Classification capabilities.

The Microsemi *AcuEdge* Technology Sound Classifier provides systems with the capability to identify specific sounds such as common smoke/fire alarm and carbon monoxide detector alert signals. The Sound Classifier can also detect the sound of breaking glass and has a programmable Energy Detector. The Energy Detector monitors for loud noises. This is done by monitoring the signal from the MIC input for signals which are above a power threshold within a specified frequency range. Identified alerts can be reported by the host.

Figure 2 - Typical Alert Monitoring and Wideband Intercom Application



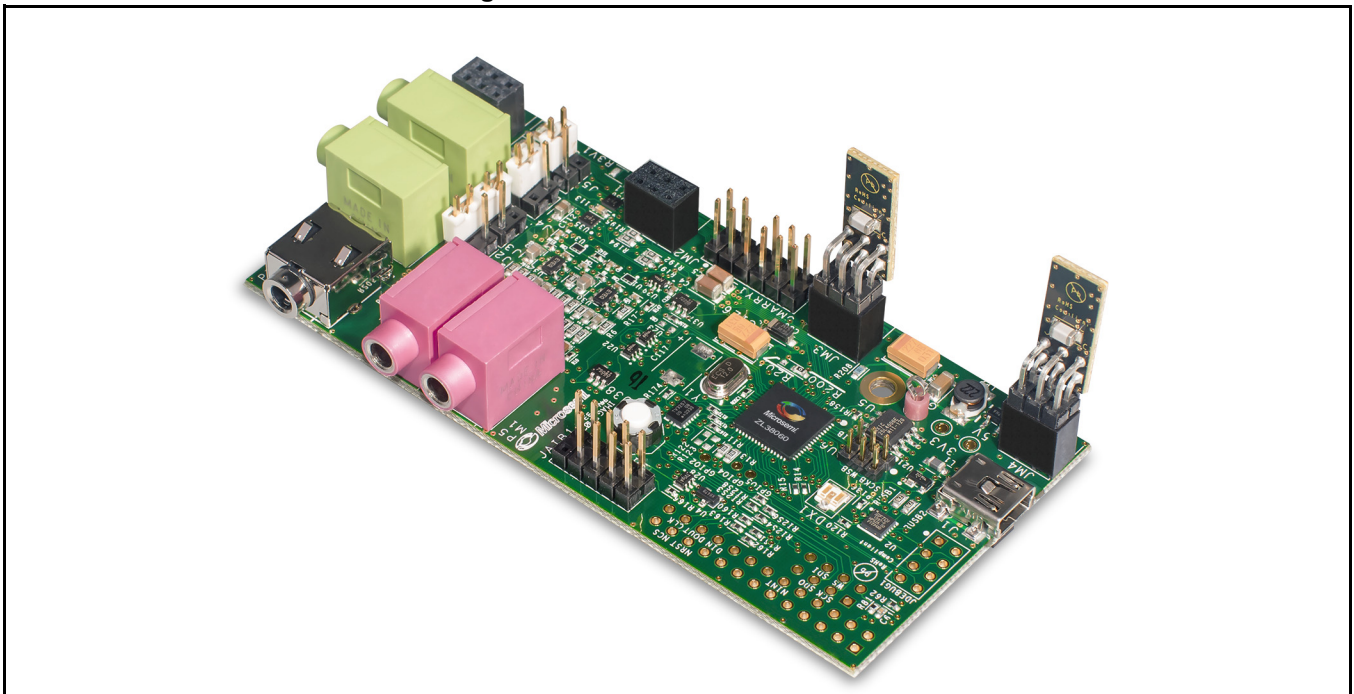
Evaluation Kit

The ZLK38000 Evaluation Kit includes all the hardware necessary to operate the ZL38062 device on the ZLE38000 Evaluation Board. The Evaluation Board provides a flexible platform to evaluate the Sound Classifier device with *AcuEdge™* Technology Firmware.

The ZLE38000 Evaluation Board provides a simple analog interface that can be connected to microphones and speakers to allow for subjective testing. The miniature size allows for easy mounting in an existing plastic enclosure.

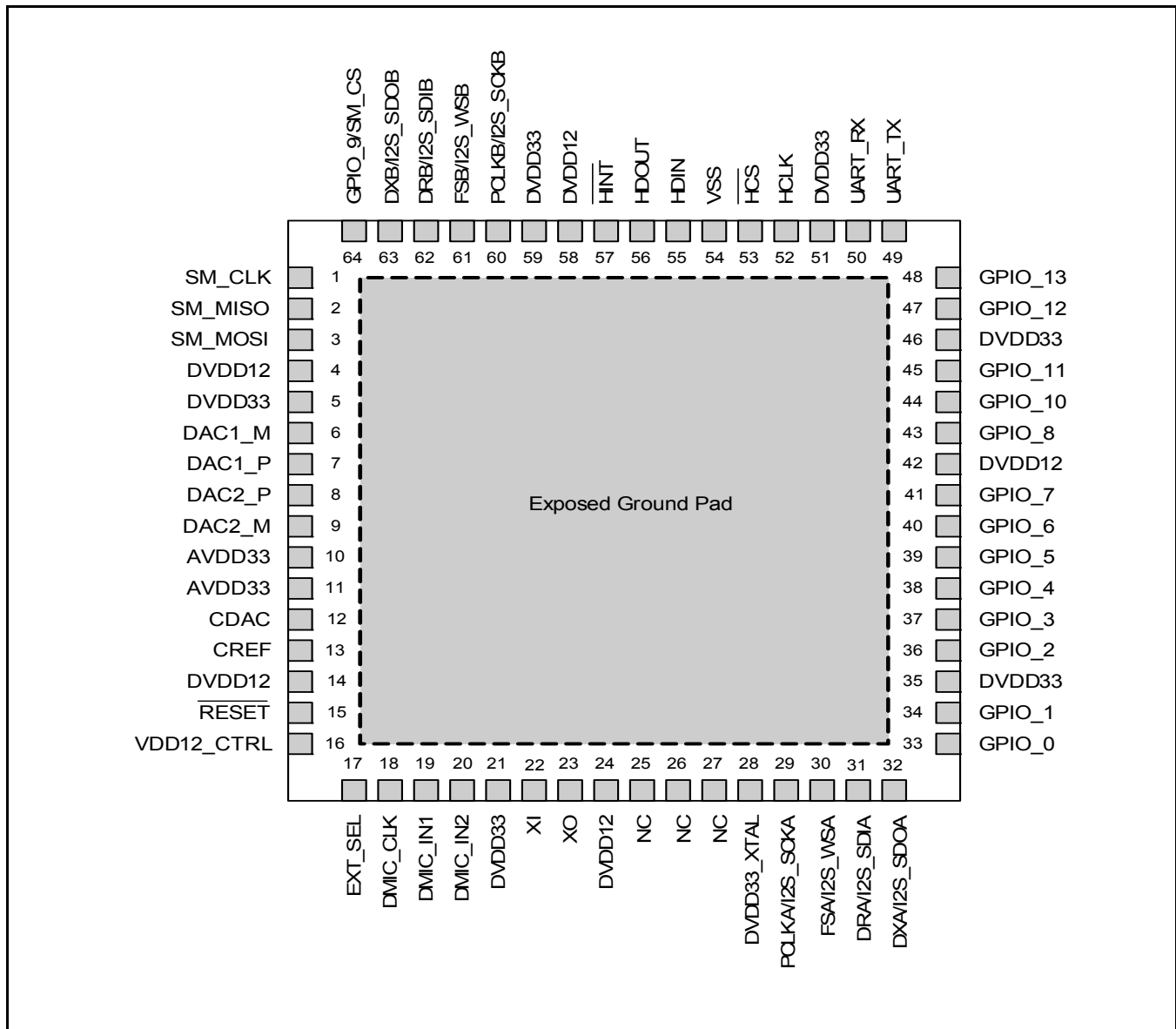
Firmware Code for the ZL38062 device and a Configuration Record for the desired demonstration platform can be downloaded into the Evaluation Board using the ZLS38000 Firmware Loader software. The ZLE38000 Evaluation Board can then be controlled using the *MiTuner™* GUI Lite Software (ZLS38508LITE) or the full *MiTuner* GUI Software package (ZLS38508). Microsemi has developed automatic tuning capability into the full *MiTuner* GUI Software to further facilitate and shorten the design process. The ZLS38508 Software package consists of the *MiTuner* GUI Software and the Audio Interface Box (AIB) Evaluation Kit (ZLE38470BADA) hardware, together performing automatic tuning of the ZL38062 device on the Evaluation Board or in a system design.

Figure 3 - ZLE38000 Evaluation Board

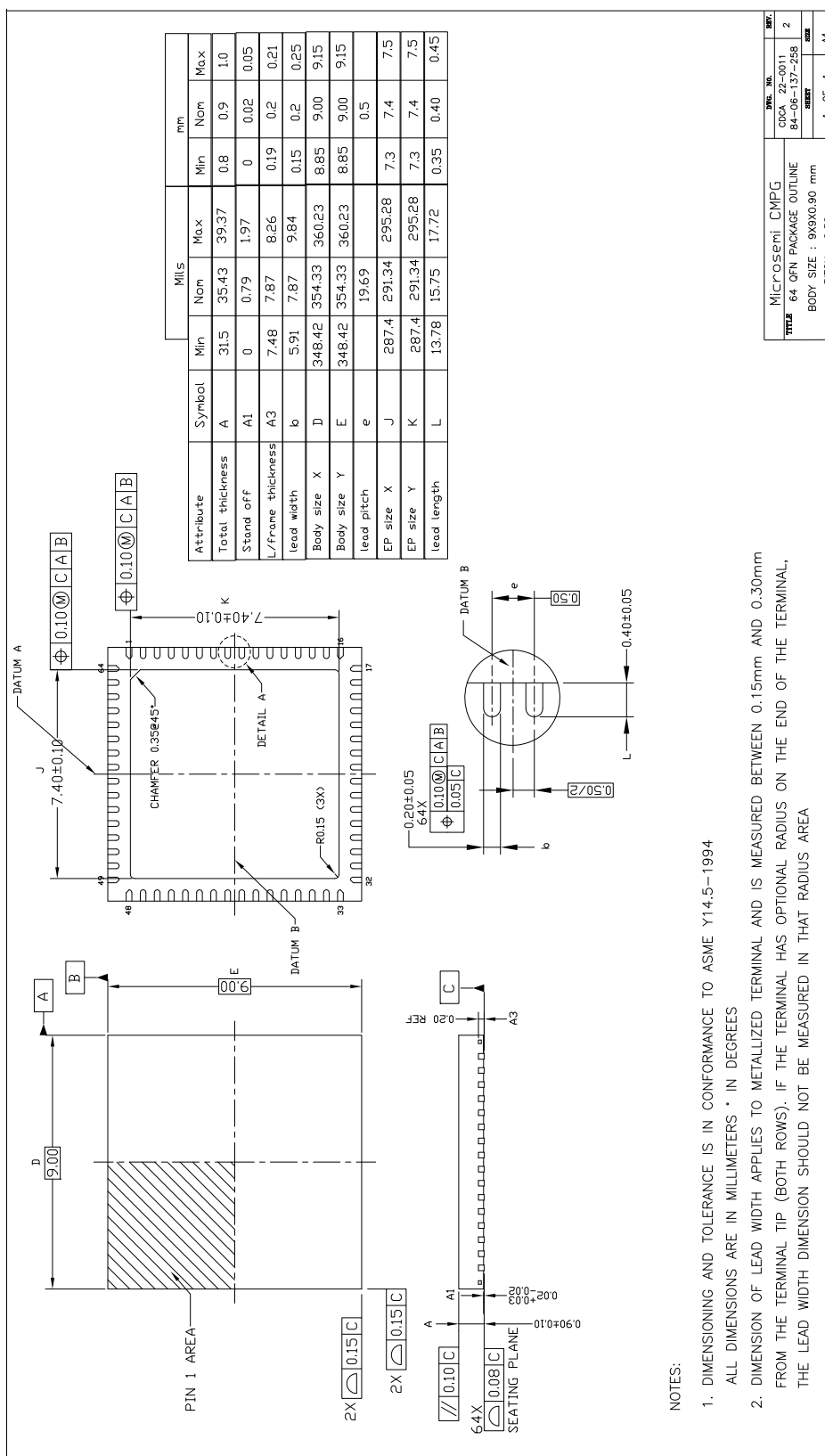


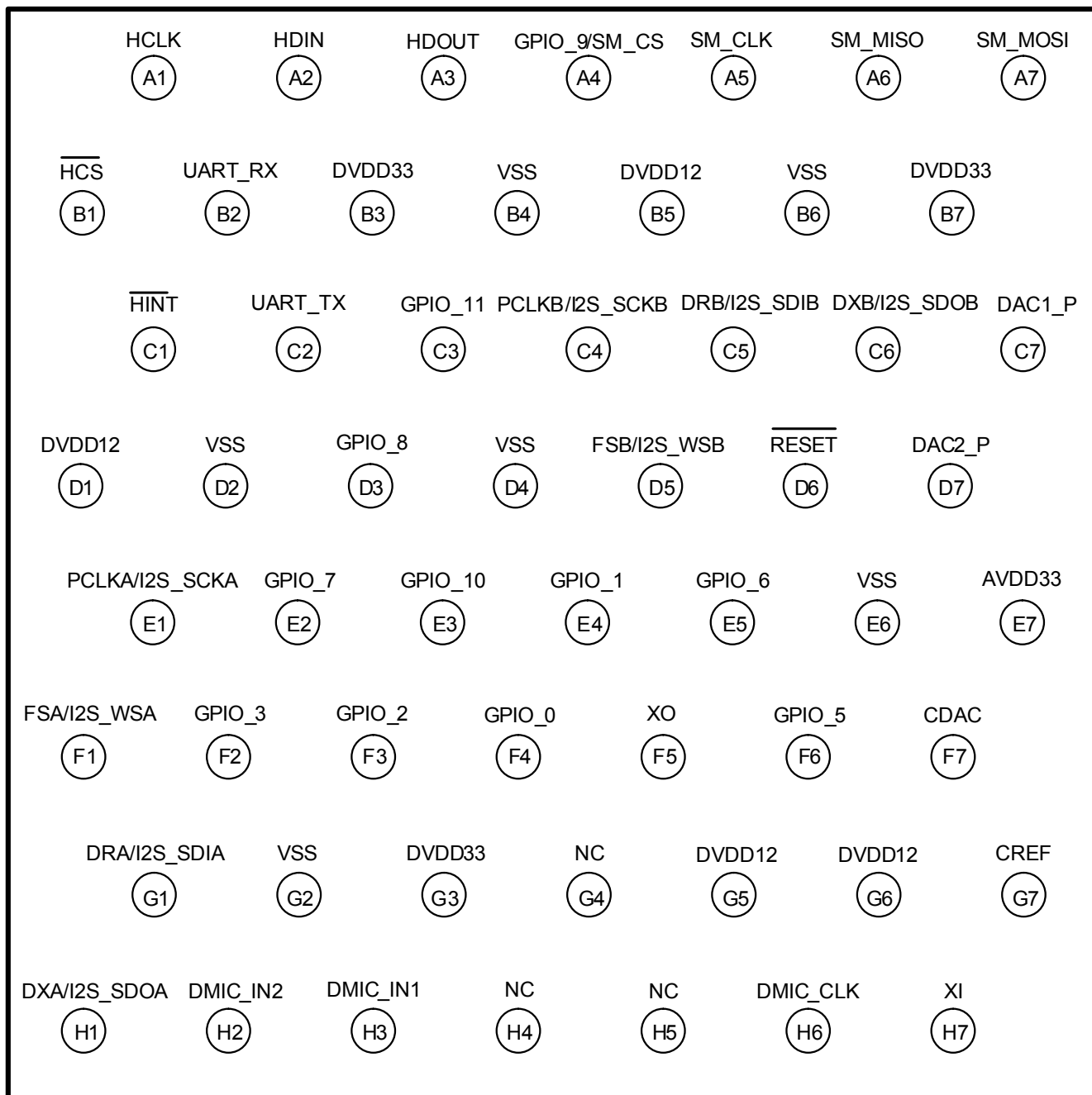
ZLK38000 Evaluation Kit Contents

- ZLE38000 Evaluation Board
- ZLS38000 Firmware Loader Software
- Serial USB to Mini USB Cable
- Headset (32 Ω), with microphone/headphone splitter adapter
- 25 foot Headset Extension Cable
- Speaker (un-powered, 4 Ω , 2.5 W)

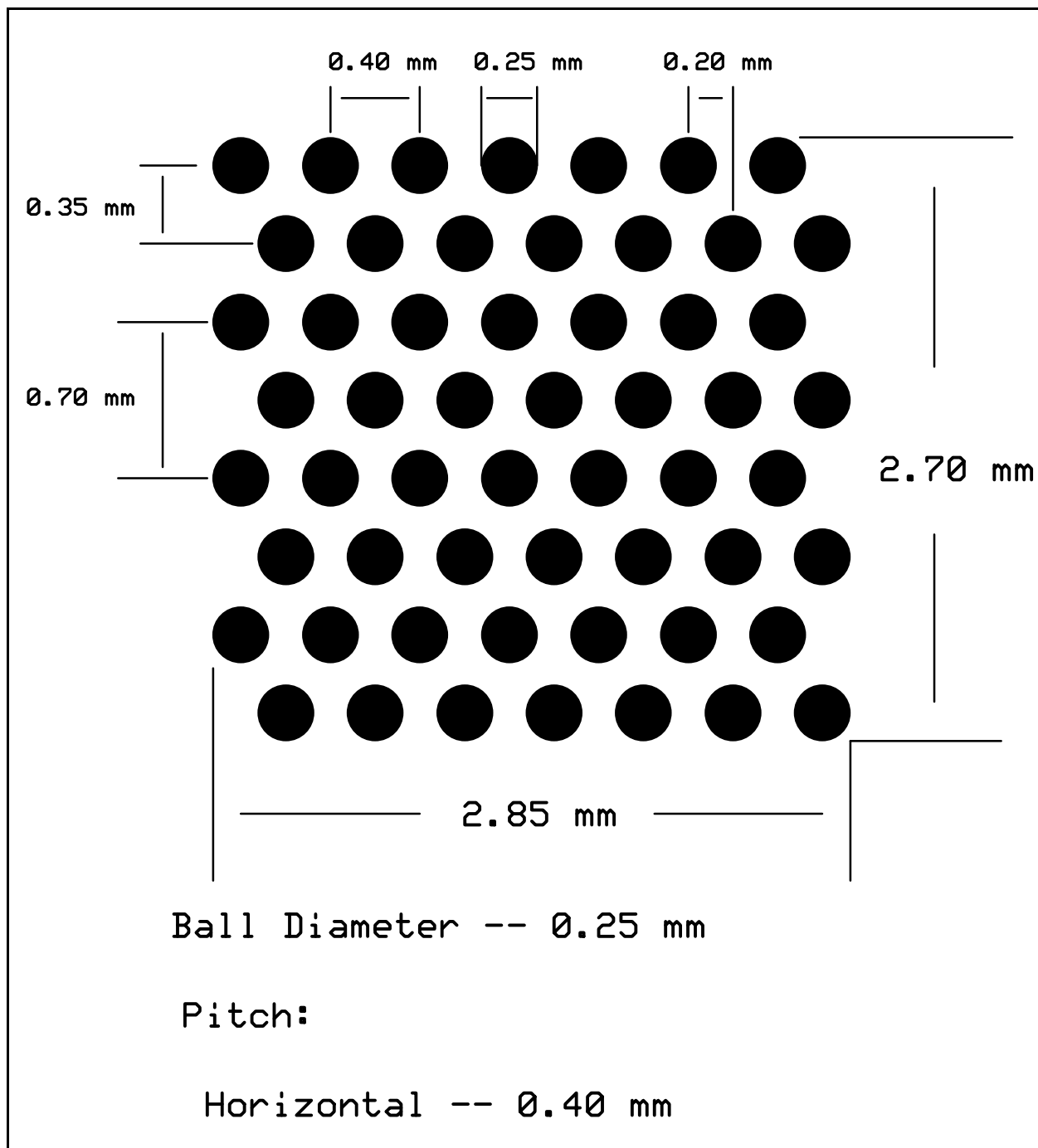
Device Pinout - Top View


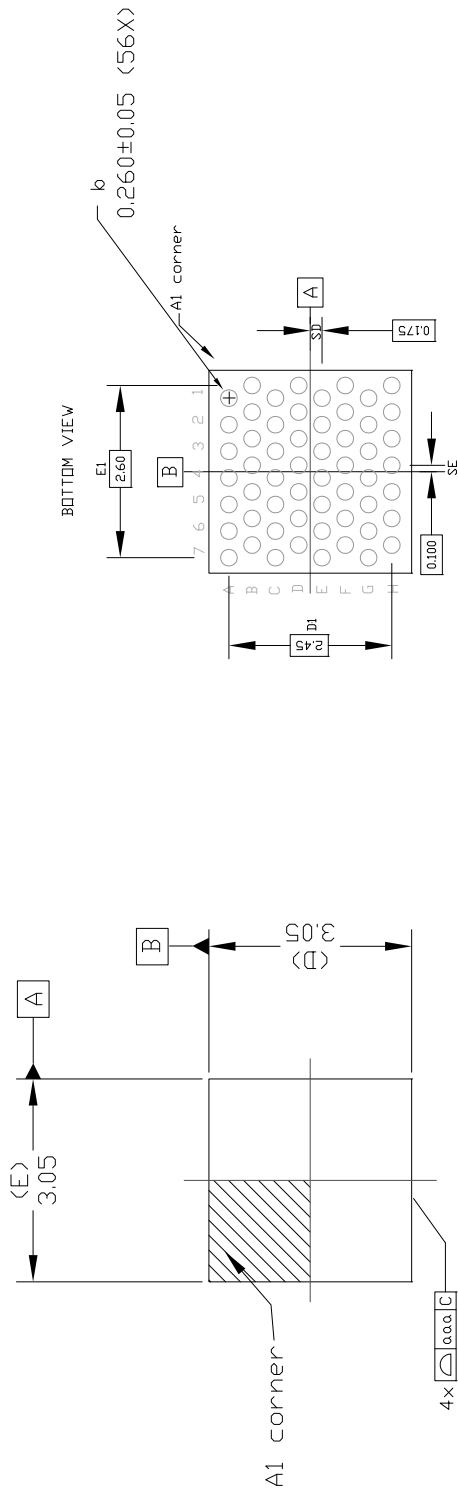
Package Outline (64-Pin QFN)



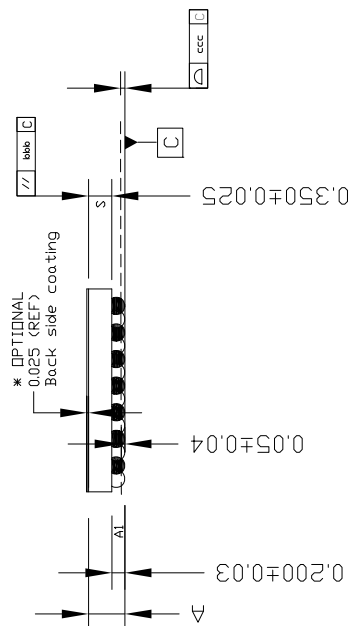
Device Pinout (56-Ball WLCSP) – Top View


Staggered Balls (56-Ball WLCSP) – Bottom View



Package Outline (56-Ball WLCSP)


Package :	Symbol	Common Dimensions (mm)
WLCSP		
Body Size:	X	E
	3.05	3.05
Row/Column Pitch :	D	0.350
	Row	0.350
	Column	0.200
Bump pitch (X) :	e	0.400
Total Thickness :	A	0.550 +/- 0.055
Die Thickness :	S	0.350 Ref.
Bump Diameter (size) :		0.250
Stand Off :	A1	0.170 ~ 0.230
Bump Width :	b	0.230 ~ 0.290
Package Edge Tolerance :	aaa	0.050
Die Flatness :	bbb	0.100
Coplanarity:	ccc	0.075
Bump Offset (Package) :	ddd	0.150
Bump Offset (Ball) :	eee	0.050
Bump Count :	n	56
Edge Ball Center to Center :	X	2.600
	Y	2.600
Center Pig To Adjacent Center Of Ball :	SE	0.100
	SB	0.175



Pin Descriptions

Table 1 - Reset Pin Description

QFN Pin #	WLCSP Ball	Name	Type	Description
15	D6	$\overline{\text{RESET}}$	Input	Reset. When low the device is in its reset state and all tristate outputs will be in a high impedance state. This input must be high for normal device operation. A 10 K Ω pull-up resistor is required on this node to DVDD33 if this pin is not continuously driven.

Table 2 - DAC Pin Descriptions

QFN Pin #	WLCSP Ball	Name	Type	Description
6	–	DAC1_M	Output	DAC 1 Minus Output. This is the negative output signal of the differential amplifier of the DAC 1. <i>Not available on the WLCSP package.</i>
7	C7	DAC1_P	Output	DAC 1 Plus Output. This is the positive output signal of the differential amplifier of the DAC 1.
9	–	DAC2_M	Output	DAC 2 Minus Output. This is the negative output signal of the differential amplifier of the DAC 2. <i>Not available on the WLCSP package.</i>
8	D7	DAC2_P	Output	DAC 2 Plus Output. This is the positive output signal of the differential amplifier of the DAC 2.
12	F7	CDAC	Output	DAC Reference. This pin requires capacitive decoupling.
13	G7	CREF	Output	Common Mode Reference. This pin requires capacitive decoupling.

Table 3 - Microphone Pin Descriptions

QFN Pin #	WLCSP Ball	Name	Type	Description
18	H6	DMIC_CLK	Output	Digital Microphone Clock Output. Clock output for digital microphones and digital electret microphone pre-amplifier devices.
19	H3	DMIC_IN1	Input	Digital Microphone Input 1. Stereo or mono digital microphone input. <i>Tie to VSS if unused.</i>
20	H2	DMIC_IN2	Input	Digital Microphone Input 2. Stereo or mono digital microphone input. <i>Tie to VSS if unused.</i>

Table 4 - TDM and I²S Ports Pin Descriptions

The ZL38052 device has two TDM interfaces, TDM-A and TDM-B. Each TDM block is capable of being a master or a slave. The ports can be configured for Pulse-Code Modulation (PCM) or Inter-IC Sound (I²S) operation. The ports conform to PCM, GCI, and I²S timing protocols.

QFN Pin #	WLCSP Ball	Name	Type	Description
29	E1	PCLKA/ I2S_SCKA	Input/ Output	<p>PCM Port A Clock (Input/Tristate Output). PCLKA is equal to the bit rate of signals DRA/DXA. In TDM master mode this clock is an output and in TDM slave mode this clock is an input.</p> <p>I²S Port A Serial Clock (Input/Tristate Output). This is the I²S port A bit clock. In I²S master mode this clock is an output and drives the bit clock input of the external slave device's peripheral converters. In I²S slave mode this clock is an input and is driven from a converter operating in master mode.</p> <p>After power-up, this signal defaults to be an input in I²S slave mode.</p> <p><i>A 100 KΩ pull-down resistor is required on this pin to VSS. If this pin is unused, tie the pin to VSS.</i></p> <p><i>When driving PCLKA/I2S_SCKA from a host, one of the following conditions must be satisfied:</i></p> <ol style="list-style-type: none"> 1. Host drives PCLKA low during reset, or 2. Host tri-states PCLKA during reset (the 100 KΩ resistor will keep PCLKA low), or 3. Host drives PCLKA at its normal frequency
30	F1	FSA/ I2S_WSA	Input/ Output	<p>CM Port A Frame Sync (Input/Tristate Output). This is the TDM frame alignment reference. This signal is an input for applications where the PCM bus is frame aligned to an external frame signal (slave mode). In master mode this signal is a frame pulse output.</p> <p>I²S Port A Word Select (Left/Right) (Input/Tristate Output). This is the I²S port A left or right word select. In I²S master mode word select is an output which drives the left/right input of the external slave device's peripheral converters. In I²S slave mode this pin is an input which is driven from a converter operating in master mode.</p> <p>After power-up, this signal defaults to be an input in I²S slave mode. <i>Tie this pin to VSS if unused.</i></p>
31	G1	DRA/ I2S_SDIA	Input	<p>PCM Port A Serial Data Stream Input. This serial data stream operates at PCLK data rates.</p> <p>I²S Port A Serial Data Input. This is the I²S port serial data input.</p> <p><i>Tie this pin to VSS if unused.</i></p>
32	H1	DXA/ I2S_SDOA	Output	<p>PCM Port A Serial Data Stream Output. This serial data stream operates at PCLK data rates.</p> <p>I²S Port A Serial Data Output. This is the I²S port serial data output.</p>

QFN Pin #	WLCSP Ball	Name	Type	Description
60	C4	PCLKB/ I2S_SCKB	Input/ Output	<p>PCM Port B Clock (Input/Tristate Output). PCLKB is equal to the bit rate of signals DRB/DXB. In TDM master mode this clock is an output and in TDM slave mode this clock is an input.</p> <p>I²S Port B Serial Clock (Input/Tristate Output). This is the I²S port B bit clock. In I²S master mode this clock is an output and drives the bit clock input of the external slave device's peripheral converters. In I²S slave mode this clock is an input and is driven from a converter operating in master mode.</p> <p>After power-up, this signal is an input in I²S slave mode. <i>Tie this pin to VSS if unused.</i></p>
61	D5	FSB/ I2S_WSB	Input/ Output	<p>PCM Port B Frame Sync (Input/Tristate Output). This is the TDM frame alignment reference. This signal is an input for applications where the PCM bus is frame aligned to an external frame signal (slave mode). In master mode this signal is a frame pulse output.</p> <p>I²S Port B Word Select (Left/Right) (Input/Tristate Output). This is the I²S port B left or right word select. In I²S master mode word select is an output which drives the left/right input of the external slave device's peripheral converters. In I²S slave mode this pin is an input which is driven from a converter operating in master mode.</p> <p>After power-up, this signal defaults to be an input in I²S slave mode. <i>Tie this pin to VSS if unused.</i></p>
62	C5	DRB/ I2S_SDIB	Input	<p>PCM Port B Serial Data Stream Input. This serial data stream operates at PCLK data rates.</p> <p>I²S Port B Serial Data Input. This is the I²S port serial data input.</p> <p><i>Tie this pin to VSS if unused.</i></p>
63	C6	DXB/ I2S_SDOB	Output	<p>PCM Port B Serial Data Stream Output. This serial data stream operates at PCLK data rates.</p> <p>I²S Port B Serial Data Output. This is the I²S port serial data output.</p>

Table 5 - HBI – SPI Slave Port Pin Descriptions

This port functions as a peripheral interface for an external controller, and supports access to the internal registers and memory of the device.

QFN Pin #	WLCSP Ball	Name	Type	Description
52	A1	HCLK	Input	<p>HBI SPI Slave Port Clock Input. Clock input for the SPI Slave port. Maximum frequency = 25 MHz.</p> <p>This input should be tied to VSS in I²C mode.</p> <p><i>Tie this pin to VSS if unused.</i></p>
53	B1	$\overline{\text{HCS}}$	Input	<p>HBI SPI Slave Chip Select Input. This active low chip select signal activates the SPI Slave port.</p> <p>HBI I²C Serial Clock Input. This pin functions as the I2C_SCLK input in I²C mode. <i>A pull-up resistor is required on this node for I²C operation.</i></p> <p><i>Tie this pin to VSS if unused.</i></p>

QFN Pin #	WLCSP Ball	Name	Type	Description
55	A2	HDIN	Input	HBI SPI Slave Port Data Input. Data input signal for the SPI Slave port. This input selects the slave address in I ² C mode. <i>Tie this pin to VSS if unused.</i>
56	A3	HDOUT	Input/Output	HBI SPI Slave Port Data Output (Tristate Output). Data output signal for the SPI Slave port. HBI I²C Serial Data (Input/Output). This pin functions as the I2C_SDA I/O in I ² C mode. <i>A pull-up resistor is required on this node for I²C operation.</i>
57	C1	$\overline{\text{HINT}}$	Output	HBI Interrupt Output. This output can be configured as either CMOS or open drain by the host.

Table 6 - Master SPI Port Pin Descriptions

This port functions as the interface to an external Flash device used to optionally Auto Boot and load the device's firmware and configuration record from external Flash memory.

QFN Pin #	WLCSP Ball	Name	Type	Description
1	A5	SM_CLK	Output	Master SPI Port Clock (Tristate Output). Clock output for the Master SPI port. Maximum frequency = 8 MHz.
2	A6	SM_MISO	Input	Master SPI Port Data Input. Data input signal for the Master SPI port.
3	A7	SM_MOSI	Output	Master SPI Port Data Output (Tristate Output). Data output signal for the Master SPI port.
64	A4	GPIO_9/ SM_ $\overline{\text{CS}}$	Input/Output	Master SPI Port Chip Select (Input Internal Pull-Up/Tristate Output). Chip select output for the Master SPI port. Shared with GPIO_9.

Table 7 - UART Pin Descriptions

The ZL38052 device incorporates a two-wire UART (Universal Asynchronous Receiver Transmitter) interface with a fixed 115.2K baud transfer rate, 8 data bits, 1 stop and no parity. The UART port can be used as a debug tool and is used for tuning purposes.

QFN Pin #	WLCSP Ball	Name	Type	Description
50	B2	UART_RX	Input	UART (Input). Receive serial data in. This port functions as a peripheral interface for an external controller and supports access to the internal registers and memory of the device.
49	C2	UART_TX	Output	UART (Tristate Output). Transmit serial data out. This port functions as a peripheral interface for an external controller and supports access to the internal registers and memory of the device.

Table 8 - GPIO Pin Descriptions

GPIO ports can be used for interrupt and event reporting, fixed function control, bootstrap options, as well as being used for general purpose I/O for communication and controlling external devices.

QFN Pin #	WLCSP Ball	Name	Type	Description
33, 34, 36	F4, E4, F3	GPIO_[0:2]	Input/Output	General Purpose I/O (Input Internal Pull-Down/Tristate Output). These pins can be configured as an input or output and are intended for low-frequency signalling.
37, 38, 39, 40, 41, 43	F2, –, F6, E5, E2, D3	GPIO_[3:8]	Input/Output	General Purpose I/O (Input Internal Pull-Down/Tristate Output). These pins can be configured as an input or output and are intended for low-frequency signalling. <i>GPIO_4 is not available on the WLCSP package.</i>
64	A4	GPIO_9/ SM_CS	Input/Output	General Purpose I/O (Input Internal Pull-Down/Tristate Output). This pin can be configured as an input or output and is intended for low-frequency signalling. Alternate functionality with SM_CS.
44, 45, 47, 48	E3, C3, –, –	GPIO_[10:13]	Input/Output	General Purpose I/O (Input Internal Pull-Down/Tristate Output). These pins can be configured as an input or output and are intended for low-frequency signalling. <i>GPIO_12 and GPIO_13 are not available on the WLCSP package.</i>

Table 9 - Oscillator Pin Descriptions

These pins are connected to a 12.000 MHz crystal or clock oscillator which drives the device's internal PLL. Alternatively, PCLKA can be used as the internal clock source.

QFN Pin #	WLCSP Ball	Name	Type	Description
22	H7	XI	Input	Crystal Oscillator Input.
23	F5	XO	Output	Crystal Oscillator Output.

Table 10 - Supply and Ground Pin Descriptions

QFN Pin #	WLCSP Ball	Name	Type	Description
17	–	EXT_SEL	Input	VDD +1.2 V Select. Select external +1.2 V supply. Tie to DVDD33 if the +1.2 V supply is to be provided externally. Tie to VSS (0 V) if the +1.2 V supply is to be generated internally. <i>Not available on the WLCSP package.</i>
16	–	VDD12_CTRL	Output	VDD +1.2 V Control. Analog control line for the voltage regulator external FET when EXT_SEL is tied to VSS. When EXT_SEL is tied to DVDD33, the VDD12_CTRL pin becomes a CMOS output which can drive the shutdown input of an external LDO. <i>Not available on the WLCSP package.</i>
4, 14, 24, 42, 58	B5, D1, G5, G6	DVDD12	Power	Core Supply. Connect to a +1.2 V $\pm 5\%$ supply. <i>Place a 100 nF, 20%, 10 V, ceramic capacitor on each pin decoupled to the VSS plane.</i>

QFN Pin #	WLCSP Ball	Name	Type	Description
5, 21, 35, 46, 51, 59	B3, B7, G3	DVDD33	Power	Digital Supply. Connect to a +3.3 V $\pm 5\%$ supply. <i>Place a 100 nF, 20%, 10 V, ceramic capacitor on each pin decoupled to the VSS plane.</i>
28	–	DVDD33_XTAL	Power	Crystal Digital Supply. For designs using a crystal or external oscillator, this pin must be connected to a +3.3 V supply source capable of delivering 10 mA. For designs that do not use a crystal or external oscillator this pin can be tied to VSS in order to save power. <i>Not available on the WLCSP package.</i>
10, 11	E7	AVDD33	Power	Analog Supply. Connect to a +3.3 V $\pm 5\%$ supply. <i>Place a 100 nF, 20%, 10 V, ceramic capacitor on each pin decoupled to the VSS plane.</i>
54	B4, B6, D2, D4, E6, G2	VSS	Ground	Ground. Connect to digital ground plane.
	–	Exposed Ground Pad	Ground	Exposed Pad Substrate Connection. Connect to VSS. This pad is at ground potential and must be soldered to the printed circuit board and connected via multiple vias to a heatsink area on the bottom of the board and to the internal ground plane. <i>Not available on the WLCSP package.</i>

Table 11 - No Connect Pin Description

QFN Pin #	WLCSP Ball	Name	Type	Description
25, 26, 27	G4, H4, H5	NC		No Connection. These pins are to be left unconnected, do not use as a tie point.

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